#### **PREAMBLE**

Innovation in Design, Manufacturing and concurrent Engineering (IDMC-2014) is highly indispensable for sustainability in competitive market and industrial growth. The recipe of globally competitive product require for key ingredients: innovative features, quality assurance, economic manufacture and rapid developments. The need to bridge the distance and time barriers in collaborative engineering is being addressed by three recent R&D thrust areas. i Intelligent Design, ii. Knowledge Management iii. Electronic commercial leading to web based engineering. The conference will comprise of technical sessions and key note addresses

#### **TOPICS**

IDMC 2014 invites research papers in the following areas (this is not an exhaustive list and papers are invited on other related topics as well):

Rapid Prototype, Precision Engineering, Concurrent Engineering, Nanotechnology, Micro Machining, MEMS, Quality Deployment Function, TAGUCHI Method, FE Modeling, CFD, Boundary Element Technique, Metal Forming, Soft Computing, Robotics, CAD/CAM, Optimization Technique, FMs, Surface Engineering, Renewable Energy, Biomedical Engineering, Information Technology, Micro-fluidics, Composites.

#### PAPER SUBMISSION

Authors are invited to submit the papers for the conference to the specified e-mail: <a href="mailto:idmc2014@gmail.com/kpmaity@gmail.com">idmc2014@gmail.com/kpmaity@gmail.com</a>. All the papers must follow the IEEE format and should not exceed more than six (6) pages. Paper to be submitted should not be previously published in other Conference/Journal. All the papers will be reviewed by the technical committee and the corresponding author of selected paper will be intimated through e-mail. A paper will be published in the conference proceedings if it is presented in the conference by one of the authors.

Last Date of submission: 31/01/2014 Intimation of Acceptance: 15/02/2014

## Camera Ready with Registration: 25/02/2014

The elected papers after peer review will be published in International Journals Advances in Computer and Electrical Engineering, International Journal of Information and Communication Technology, International Journal of Computational Vision and Robotics. The conference proceeding is likely to be published in Springer Book Series on Modeling and optimization in Science and Technology[MOST].

#### **ABOUT NIT ROURKELA**

The conference will be organized by the department of Mechanical Engineering, National Institute of Technology (NIT), Rourkela. It is one of the premier national level institutions for technical education in the country and is funded by the Government of India. It is situated at the eastern end of Rourkela steel city, beyond Sector-1 over an area of 262 hectares of land. NIT Rourkela has seventeen academic Departments which offer B.Tech, M.Tech, MBA and PhD programs in various areas of Engineering, Technology and Management.

### ABOUT MECHANICAL ENGG. DEPARTMENT

Department of Mechanical Engineering, NIT Rourkela was established in 1961. The Department currently runs four M.Tech programmes with the specializations in (i)Production Engineering, (ii) Machine Design & Analysis, iii) Thermal Engineering (iv) Industrial Refrigeration and cryogenics. The Department also offers a dual degree M Tech with specialization in Mechatronics and Automation. Faculty members are involved in DIFFERENT R&D projects sponsored by DRDO, DRNS, CSIR, DST, Naval Engg., DAE etc

### **REGISTRATION**

Student/Research Scholars	Rs.1000/-
Faculty for Academics	Rs.2000/-
International Participants	100 USD

R&D/Industry Delegates	Rs.3000/-
Product Exhibition	Rs.5000/-

Registration charges include conference kits and fooding. The attached registration form shall be filled and sent along with the registration fee to the contact person latest by Feb/25, 2014. Registration Fee shall be paid by Demand Draft in favour of "IDMC 2014" payable at SBI, NIT Branch, Rourkela (code- 2109). The participants need to bear the accommodation by their own. For the guest house accommodation purpose kindly contact the convener in advance.

#### FOR ADVERTISEMENT

	Back Cove	r Souvneir	Colours	Rs. 30,000
	Full Page	Colour		Rs. 20,000
	Full Page	B/W		Rs. 10,000
$\triangleright$	Half Page	B/W		Rs. 5,000

### ADDRESS FOR CORRESPONDENCE

# Prof. K. P. Maity (Coordinator, IDMC 2014)

Department of Mechanical Engineering National Institute of Technology Rourkela – 769008, Orissa

Phone: 0661 - 2462417 (O), +91-8763432840 (M)

Email: <a href="mailto:idmc2014@gmail.com">idmc2014@gmail.com</a>, kpmaity@gmail.com,

International Conference on
Innovation in Design,
Manufacturing and Concurrent
Engineering
(IDMC 2014)
01st-03rd, March 2014

### **REGISTRATION FORM**

1. Name:
(Capital Letters with Surname underlined)
2. Paper ID:
3. Designation:
4. Organization:
5. Mailing Address:
Phone
FAX
E-mail
6. Accommodation required: YES / NO
7. Registration Fee:
DD NoDate
Issuing Bank:

Date

SIGNATURE

## **ADVISORY COMMITEE**

Prof. Debendra Das, University of Alaska, USA Prof. S. K. Kassegne, San Diego State University, USA

Prof. A. K. Nath, IIT Khagrapur

Prof. B Ravi, IIT Bombay

Prof. BG Gurumoorthy, IISC Banglore

Prof Rudrapratap IISc Banglore

Dr H R Grover CSIR

Dr Miland Kulkarni DST

Dr N Krishnamurthy BARC

Dr Kulwant Singh BARC

## **ORGANIZING COMMITEE**

Prof. K.P.Maity	Prof. R.K.Sahoo
Prof.S.S.Mohapatra	Prof P K Ray
Prof S K Sahoo	Prof DRK Parhi
Prof S K Acharya	Prof. S.K.Patel
Prof. S.C.Mohanty	Prof. R.K.Behera
Prof.S.Biswas	Prof S Gangopadhyay
Prof. S.Murugan	Prof. T.Roy
Prof.H.Ray	Prof.S.K.Panda
Prof. S.Ghosh	Prof. M.K.Moharana
Prof.M.Masanta	Prof.S.K.Behera
Prof. A.Mitra	Prof B. Chittibabu
Prof.S.Datta	Prof. A. Satapathy
Prof K. Satyababu	Prof. J. Srinivas
Prof. A. K. Satapathy	

International Conference on
Innovation in Design,
Manufacturing and Concurrent
Engineering
(IDMC 2014)
01-03, March 2014

Organized by





PATRON
Prof. S.K.Sarangi FNAE
Director, NIT Rourkela

<u>CHAIRMAN & CONVENER</u> Prof. K. P. Maity, HOD Mech.

Organized by

DEPT. OF MECHANICAL ENGINEERING NATIONAL INSTITUTE OF TECHNOLOGY ROURKELA - 769 008, ODISHA